

# MOSFET - Power, Single N-Channel, SUPERFET<sup>®</sup>, EASY with Zener Diode, PQFN88-4L 600 V, 280 mΩ, 13 A NTMT280N60S5Z

#### **Description**

SUPERFET V MOSFET Easy Drive series combines excellent switching performance without sacrificing ease of use and EMI issues for both hard and soft switching topologies. The Power88 package which is an ultraslim SMD package offers excellent switching performance by providing kelvin source configuration and lower parasitic source inductance.

#### Features

- 650 V @  $T_J = 150$ °C
- Typ.  $R_{DS(on)} = 224 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free / BFR Free and are RoHS Compliant

#### **Applications**

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Lighting / Charger / Adapter / Industrial Power Supplies

## ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub> = 25°C, Unless otherwise noted)

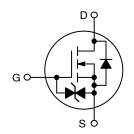
Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		$V_{DSS}$	600	V
Gate-to-Source Voltage	DC	$V_{GS}$	±20	V
	AC (f > 1 Hz)		±20	
Continuous Drain Current	T <sub>C</sub> = 25°C	I <sub>D</sub>	13	Α
	T <sub>C</sub> = 100°C		8	
Power Dissipation	$T_C = 25^{\circ}C$	$P_{D}$	89	W
Pulsed Drain Current (Note 1)	$T_C = 25^{\circ}C$	$I_{DM}$	39	Α
Pulsed Source Current (Body Diode) (Note 1)		I <sub>SM</sub>	39	Α
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C
Source Current (Body Diode)		I <sub>S</sub>	13	Α
Single Pulse Avalanche Energy	$I_L = 2.9 A$ $R_G = 25 \Omega$	E <sub>AS</sub>	82	mJ
Avalanche Current		I <sub>AS</sub>	2.9	Α
Repetitive Avalanche Energy (Note 1)		E <sub>AR</sub>	0.89	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			50	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{SD} \le 5.5 \text{ A}$ , di/dt  $\le 200 \text{ A/s}$ ,  $V_{DD} \le 400 \text{ V}$ , starting  $T_J = 25 ^{\circ}\text{C}$ .

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
600 V	280 m $\Omega$ @ V <sub>GS</sub> = 10 V	13 A

#### **N-CHANNEL MOSFET**





TDFN4 8x8 2P CASE 520AB

#### MARKING DIAGRAM

NTMT280 N60S5Z AWLYWW

 NTMT280N60S5Z
 = Specific Device Code

 A
 = Assembly Location

 WL
 = Wafer Lot

 Y
 = Year

 WW
 = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTMT280N60S5Z	TDFN4	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

1

<sup>\*</sup>Drain current limited by maximum junction temperature.

## THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	1.4	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	45	

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	-	-	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	630	-	mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 600 V, T <sub>J</sub> = 25°C	-	-	1	μΑ	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	-	-	±5	μΑ	
ON CHARACTERISTICS							
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.5 A, T <sub>J</sub> = 25°C	-	224	280	mΩ	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{GS} = V_{DS}$ , $I_D = 1$ mA, $T_J = 25$ °C	2.4	-	4	V	
Forward Trans-conductance	9FS	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 5.5 A	-	10.6	-	S	
CHARGES, CAPACITANCES & GATE	RESISTANCE						
Input Capacitance	C <sub>ISS</sub>	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	979	-	pF	
Output Capacitance	C <sub>OSS</sub>		-	18.5	-	1 !	
Time Related Output Capacitance	C <sub>OSS(tr.)</sub>	$I_D$ = Constant, $V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	277	-	7	
Energy Related Output Capacitance	C <sub>OSS(er.)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	32.2	-		
Total Gate Charge	Q <sub>G(tot)</sub>	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 5.5 A, V <sub>GS</sub> = 10 V	-	18.1	-	nC	
Gate-to-Source Charge	$Q_{GS}$		-	4.54	-		
Gate-to-Drain Charge	$Q_{GD}$		-	4.96	-		
Gate Resistance	$R_{G}$	f = 1 MHz	-	5.1	-	Ω	
SWITCHING CHARACTERISTICS							
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	16.1	-	ns	
Rise Time	t <sub>r</sub>	$I_D = 5.5 \text{ A}, R_G = 12 \Omega$	-	4.62	-		
Turn-Off Delay Time	t <sub>d(off)</sub>		-	53.4	-		
Fall Time	t <sub>f</sub>		-	4.7	-		
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS						
Forward Diode Voltage	$V_{SD}$	$I_{SD} = 5.5 \text{ A}, V_{GS} = 0 \text{ V}, T_{J} = 25^{\circ}\text{C}$	-	-	1.2	V	
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 5.5 A,	-	230	-	ns	
Reverse Recovery Charge	Q <sub>RR</sub>	dI/dt = 100 A/μs, V <sub>DD</sub> = 400 V	-	2115	-	nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

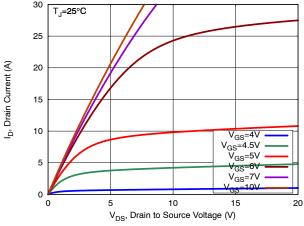


Figure 1. On-Region Characteristics

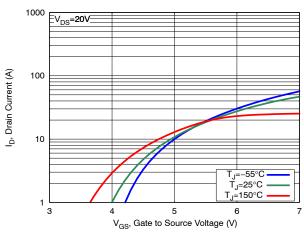


Figure 2. Transfer Characteristics

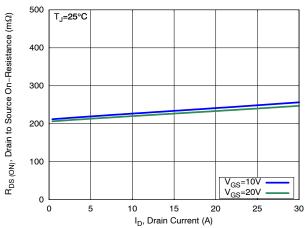


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

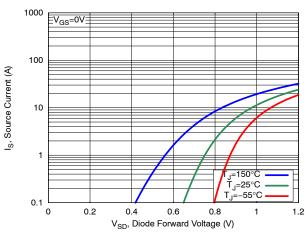


Figure 4. Diode Forward Voltage vs. Source Current

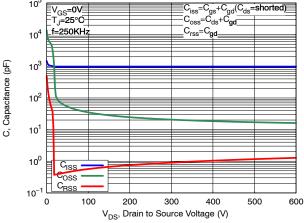


Figure 5. Capacitance Characteristics

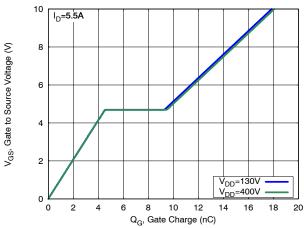


Figure 6. Gate Charge Characteristics

# **TYPICAL CHARACTERISTICS**

ID, Drain Current (A)

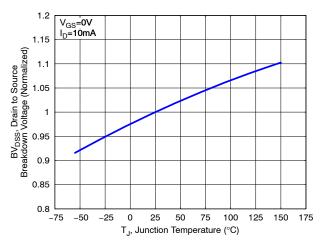


Figure 8. Breakdown Voltage Variation vs. Temperature

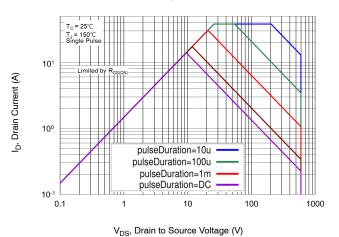


Figure 9. Maximum Safe Operating Area

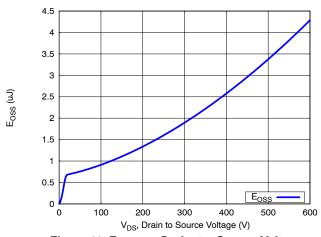


Figure 11. Eoss vs. Drain-to-Source Voltage

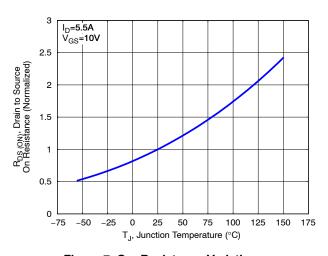


Figure 7. On–Resistance Variation vs. Temperature

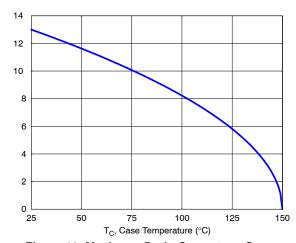


Figure 10. Maximum Drain Current vs. Case Temperature

# **TYPICAL CHARACTERISTICS**

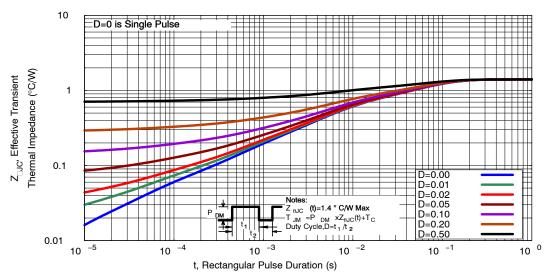
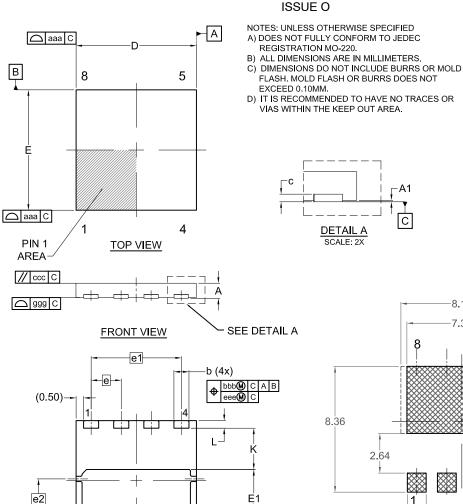


Figure 12. Transient Thermal Impedance

#### **PACKAGE DIMENSIONS**

## TDFN4 8x8, 2P CASE 520AB



(0.40)

-(0.40)

-D1

⊕ fff@ C A B

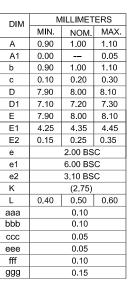
**BOTTOM VIEW** 

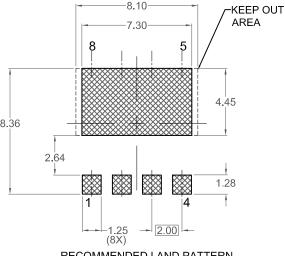
♦ fffM C A B

(1.03)

E2

(6x)





-8.10

#### RECOMMENDED LAND PATTERN

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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